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Attorney Dkt: HRL/007-03

HRL Dkt: 030204

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

	In re Application of: Pikulski)		
) Gr	oup Art	Unit: 1725
5	Entitled: MICROPARTICLE LOADED)		
	SOLDER PREFORM ALLOWING BOND SITE) Ex	aminer:	Johnson J.
	CONTROL OF DEVICE SPACING AT)		
	MICRON, SUBMICRON, AND)		
	NANOSTRUCTURE SCALE)		
)		
10	Serial No.: 10/762,901)		
) .		
	Filing Date: January 22, 2004)		

RESPONSE TO OFFICE ACTION DATED 10/20/2006

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

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In response to the Office Action dated October 20, 2006, Applicant hereby respectfully requests reconsideration of the claims in view of the following amendments and remarks.

The Claim amendment begin on page 2.

The Remarks begin on page 10.